

**Gate resistor installed  
Dual N-channel MOSFET**

**KFC4B21210L  
Data Sheet**

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### 1. GENERAL DESCRIPTION

Gate resistor installed Dual N-channel MOSFET  
For lithium-ion secondary battery protection circuits

### 2. FEATURES

- Source-source ON resistance:  $R_{ss(on)}$  typ. = 13 mΩ (VGS = 3.8 V)
- CSP (Chip Size Package)
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1)

### 3. MARKING SYMBOL: 18

### 4. PACKAGING

Embossed type (Thermo-compression sealing): 20,000 pcs / reel (standard)

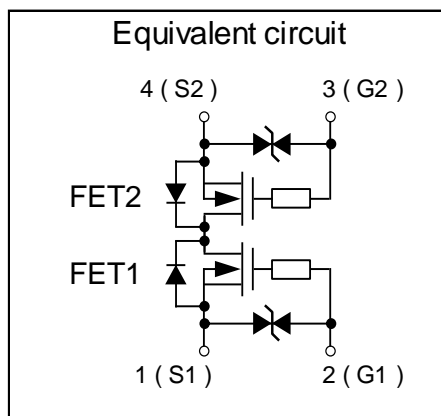
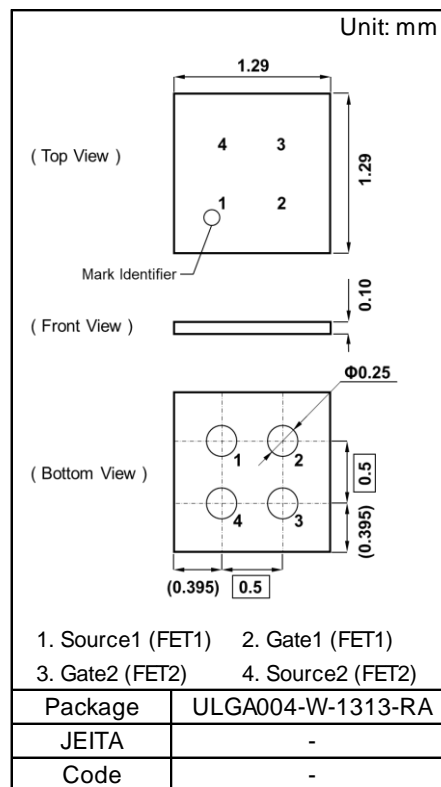
### 5. ABSOLUTE MAXIMUM RATINGS $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Source-source Voltage	VSS	12	V
Gate-source Voltage	VGS	±8	V
Source Current	DC	IS1 <sup>*1</sup>	4.7
		IS2 <sup>*2</sup>	7.7
		IS3 <sup>*3</sup>	10.4
	Pulsed <sup>*4</sup>	ISp	47
Total Power Dissipation	DC	PD1 <sup>*1</sup>	0.37
		PD2 <sup>*2</sup>	1.0
		PD3 <sup>*3</sup>	1.8
Channel Temperature	Tch	150	°C
Storage Temperature Range	Tstg	-55 to +150	°C

### 6. THERMAL CHARACTERISTICS $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Thermal Resistance (ch-a)	Rth1 <sup>*1</sup>	338	°C / W
	Rth2 <sup>*2</sup>	125	
	Rth3 <sup>*3</sup>	69	

- Note
- \*1 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm), FR4 board partially covered with copper pad (18 mm<sup>2</sup> area, 36 μm thickness).
  - \*2 Mounted on FR4 board (25.4 mm x 25.4 mm x t1.0 mm), FR4 board fully covered with copper pad (613 mm<sup>2</sup> area, 36 μm thickness).
  - \*3 Mounted on Ceramic board (70 mm x 70 mm x t1.0 mm).
  - \*4 t = 10 μs, Duty Cycle ≤ 1 %



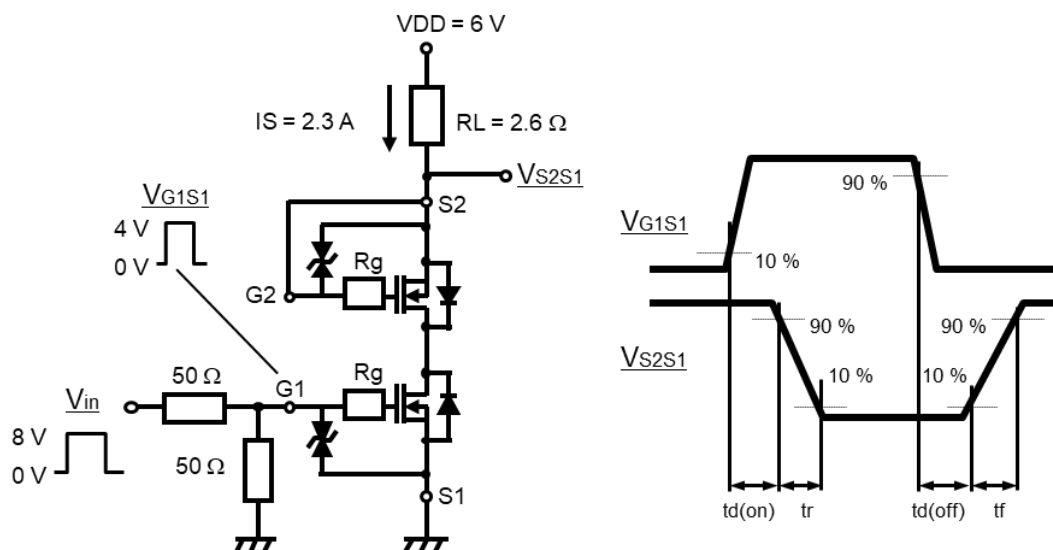
7. ELECTRICAL CHARACTERISTICS Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	12			V
Zero Gate Voltage Source Current	ISSS	VSS = 12 V, VGS = 0 V			1.0	μA
Gate-Source Leakage Current	IGSS1	VGS = ±8 V, VSS = 0 V			±10	μA
	IGSS2	VGS = ±5 V, VSS = 0 V			±1.0	
Gate-source Threshold Voltage	Vth	IS = 0.31 mA, VSS = 6 V	0.35	0.90	1.40	V
Source-source On-state Resistance	RSS(on)1	IS = 2.3 A, VGS = 4.5 V	8.0	12.0	14.5	mΩ
	RSS(on)2	IS = 2.3 A, VGS = 3.8 V	9.0	13.0	16.5	
	RSS(on)3	IS = 2.3 A, VGS = 3.1 V	9.5	14.0	21.5	
	RSS(on)4	IS = 2.3 A, VGS = 2.5 V	10.0	17.0	31.5	
Body Diode Forward Voltage	VF(s-s)	IF = 2.3 A, VGS = 0 V		0.7	1.0	V
Input Capacitance *1	Ciss	VSS = 10 V, VGS = 0 V, f = 1 kHz		1140		pF
Output Capacitance *1	Coss			180		
Reverse Transfer Capacitance *1	Crss			140		
Turn-on Delay Time *1,*2	td(on)	VDD = 6 V, VGS = 0 to 4 V		0.33		μs
Rise Time *1,*2	tr	IS = 2.3 A		0.56		
Turn-off Delay Time *1,*2	td(off)	VDD = 6 V, VGS = 4 to 0 V		1.57		μs
Fall Time *1,*2	tf	IS = 2.3 A		0.86		
Total Gate Charge *1	Qg	VDD = 6 V		9.4		nC
Gate-source Charge *1	Qgs	VGS = 0 to 4 V		2.6		
Gate-drain Charge *1	Qgd	IS = 4.7 A		1.9		

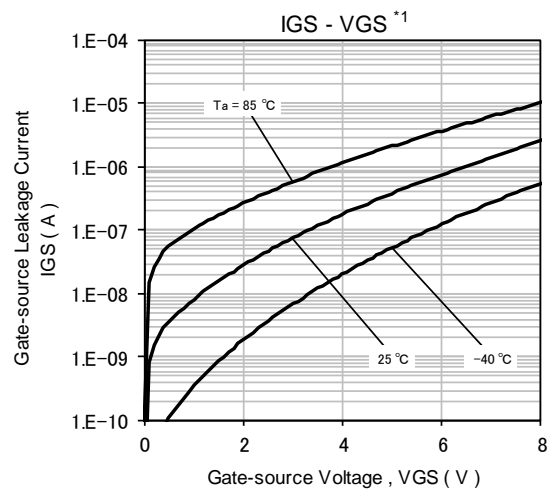
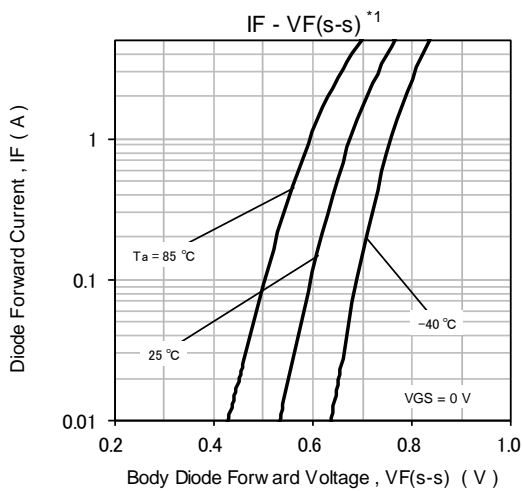
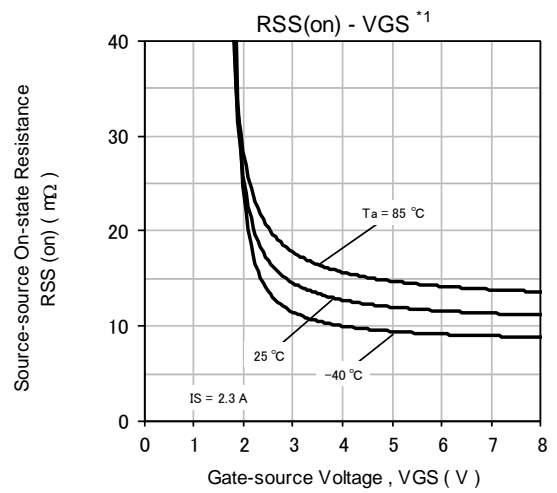
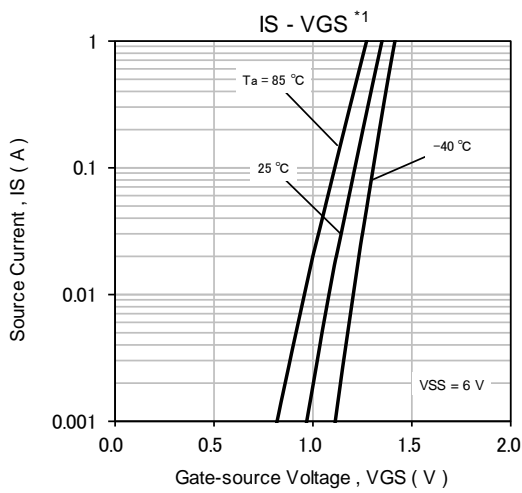
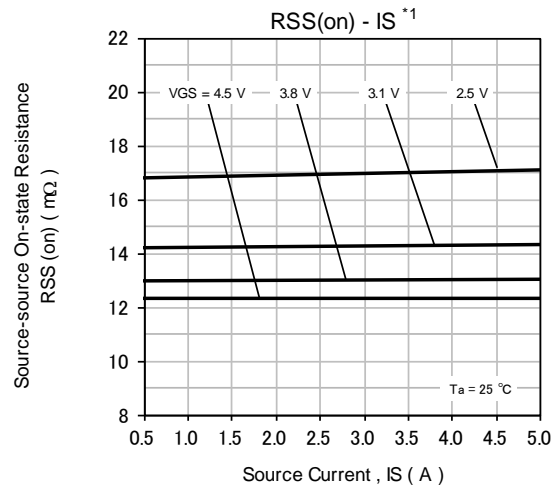
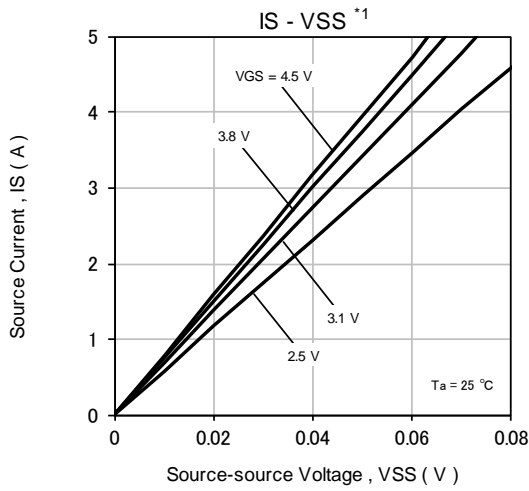
Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

\*1 Guaranteed by design, not subject to production testing

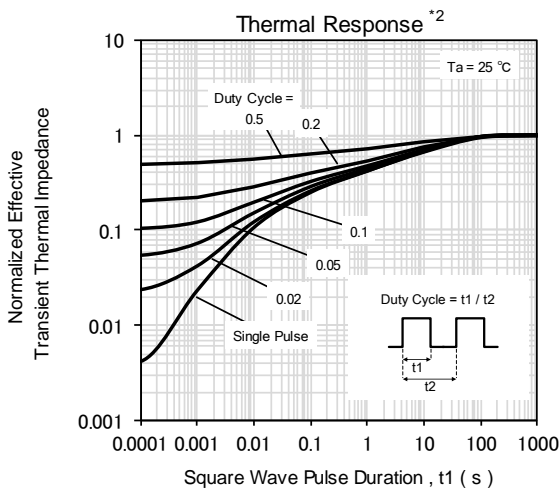
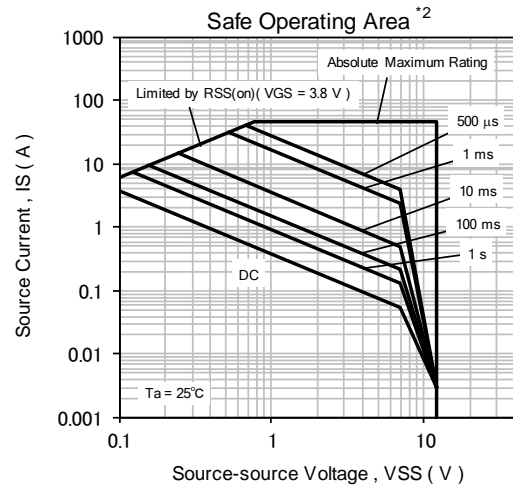
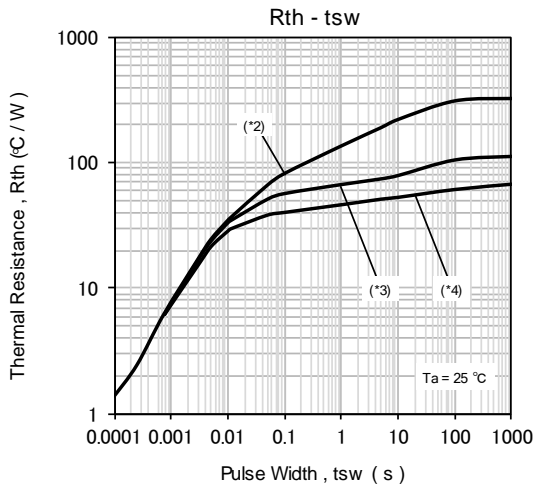
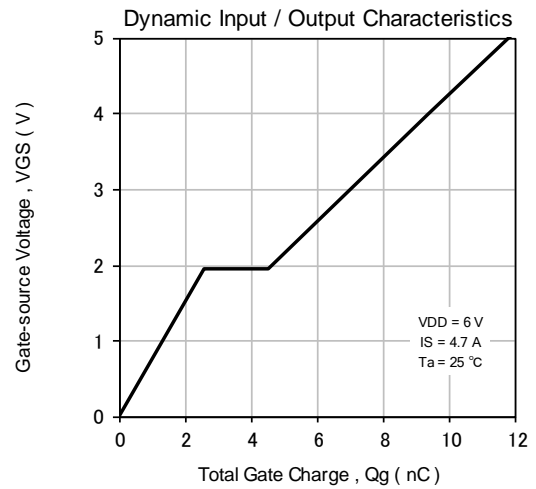
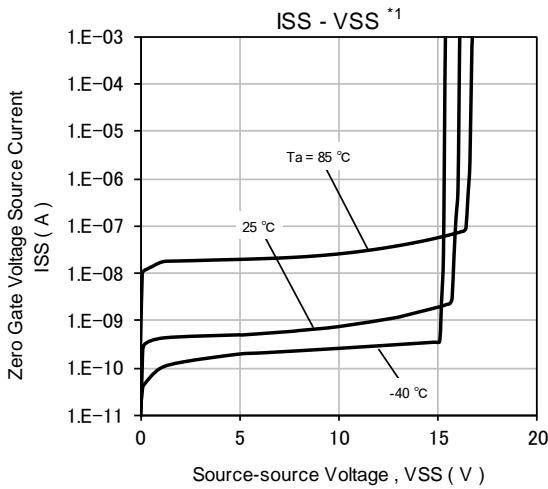
\*2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time



8. TECHNICAL DATA (Reference)



TECHNICAL DATA (Reference)

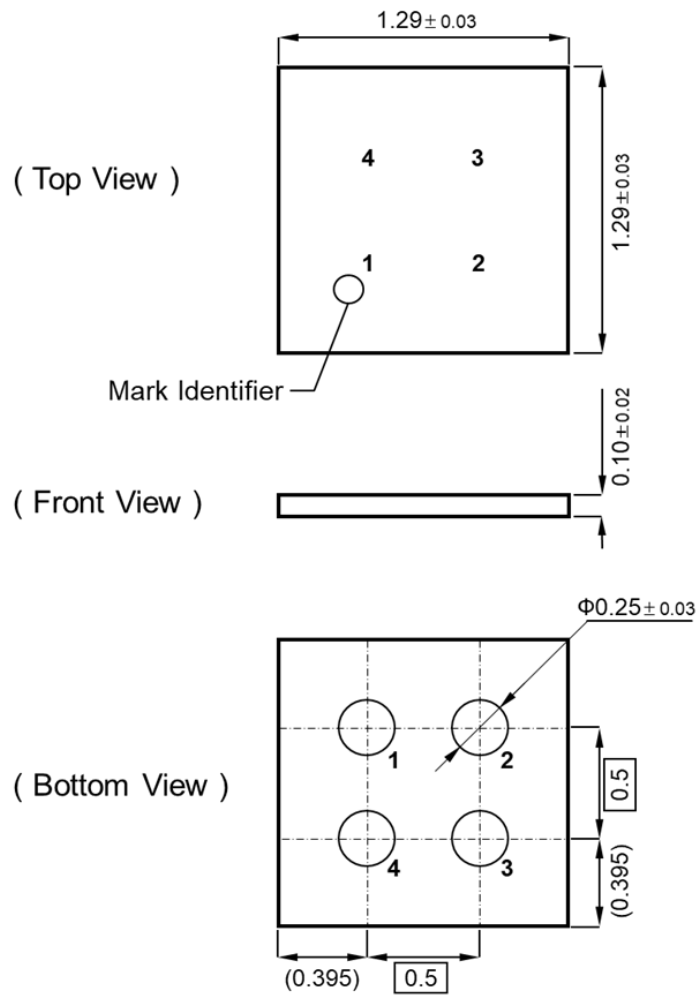


Note

- \*1 Pulse measurement.
- \*2 Mounted on FR4 board ( 25.4 mm × 25.4 mm × t1.0 mm ). FR4 board partially covered with copper pad ( 18 mm<sup>2</sup> area, 36 μm thickness ).
- \*3 Mounted on FR4 board ( 25.4 mm × 25.4 mm × t1.0 mm ). FR4 board fully covered with copper pad ( 613 mm<sup>2</sup> area, 36 μm thickness ).
- \*4 Mounted on ceramic board ( 70 mm × 70 mm × t1.0 mm ).

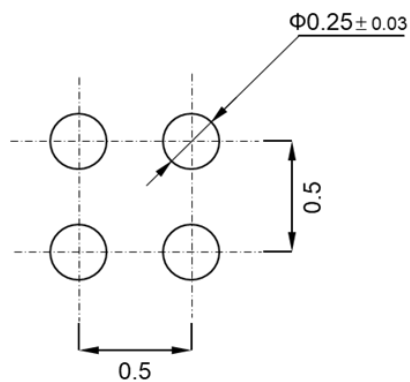
9. OUTLINE

Unit : mm



10. LAND & STENCIL PATTERN (Reference)

Unit : mm



11. REVISION HISTORY

Date	Revision	Description
2021.2.5	1.00	1. initially issued.

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